

**Amendments to the Specification:**

Please replace paragraph 29 with the following amended paragraph:

-- However, the glass passivation may not be used for wafer size greater than 5 inch, e.g., 6 inch or greater. The present inventors noted that wafers processed with glass passivation showed tendency to bend ~~id~~ if 6 inch wafer were used. This bending problem results from the differences between the thermal expansion coefficients of the glass and silicon wafer. The bending is not a significant issue under the current state of art, which uses 5 inch wafer, for fabricating power devices. An appropriate substitute for glass would be needed in order to migrate to 6 inch or 8 inch wafers. Also, the glass passivation is sensitive to the humidity and requires higher manufacturing costs since separate equipment is need to spray on the glass to the wafer. --